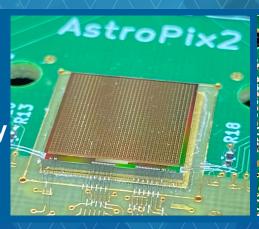
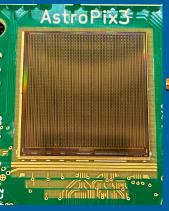
Barrel Imaging Calorimeter Meeting

June 12-16, 2023

AstroPix Setup at Fermilab Testbeam Facility







Manoj Jadhav Argonne National Laboratory





## Imaging layers technology

## Imaging layers based on AstroPix sensors

- 180nm HV-CMOS MAPS sensor
- Developed for AMEGOX NASA mission
- Based on ATLASpix3 <u>arXiv:2109.13409</u> [astro-ph.IM]

#### **Key features:**

- Very low power dissipation < 1.5 mW/cm<sup>2</sup>
- The good energy resolution (<10% @ 60 keV)
- 500 μm X 500 μm pixel size
- Sensor thickness of 700 μm
- Time resolution ~ 3.25 ns (V4)
- Perfect for Calorimetry, with some open studies!

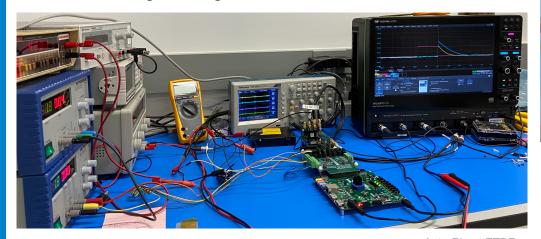
# Quad Chip 4cm APS Quad Chip (95x) APS Array 35 x 35 pixels Digital periphery Common Bus Bar APS K1100 Support Frame Stand-Offs (16x) Corner Blocks (4x) AMEGO-X Support system AMO49

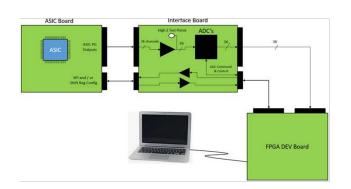
#### **Project Goal**

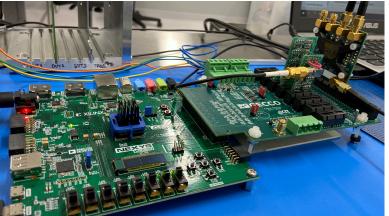
- Assess the feasibility of using an AstroPix-like sensor in an imaging electromagnetic calorimeter environment based on measurements with the test-beam and bench test setup.
- Is the chip readout scheme optimal for calorimetry? → Tests of chip responses to electromagnetic and hadronic showers in the beam environment
- How radiation hard is the chip? → Irradiation tests in a high-intensity proton beam

# **AstroPix Setup**

- \* Full bench set available
- \* AstroPix testing setup NexysVideo FPGA, GECCO
  - Analog (DSO) and Digital data acquisition
- AstroPix chip mounting on chip carrier boards and wire-boding
- Sensor electric characterization using a probe station
- Transient current Technique (TCT)
  - Depletion depth analysis
  - Charge sharing







**GE**neric **C**onfiguration and **CO**ntrol System (GECCO) Connection to FPGA - NexysVideo (Xilinx Artrix-7) Vivado Design Suite HLx to program ASIC chip

# Imaging layers R&D

### AstroPix sensor validation testing

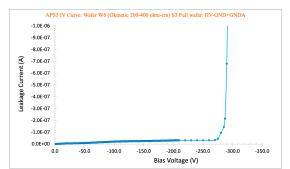
- Bench tests with AstroPix v2
  - Energy resolution studies
  - Noise measurements
  - Digital data acquisition
  - Sensor characterisation (IV, edge-TCT, depletion depth)

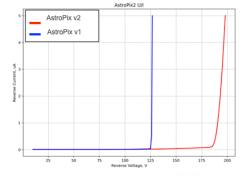


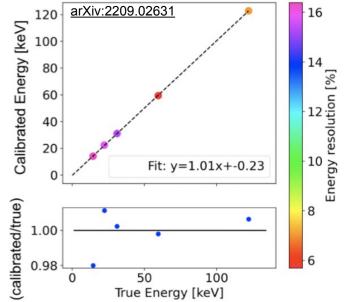
- Validate detector performance at 120 GeV proton beam
- Intergration of AstroPix with ATLAS telescope
- AstroPix telescope tracker (4 layers of AstroPix)
- Feasibility with Calorimeter environment with pions/electron beam at FTBF with tungsten radiator, readout aspects (ANL LDRD grant)

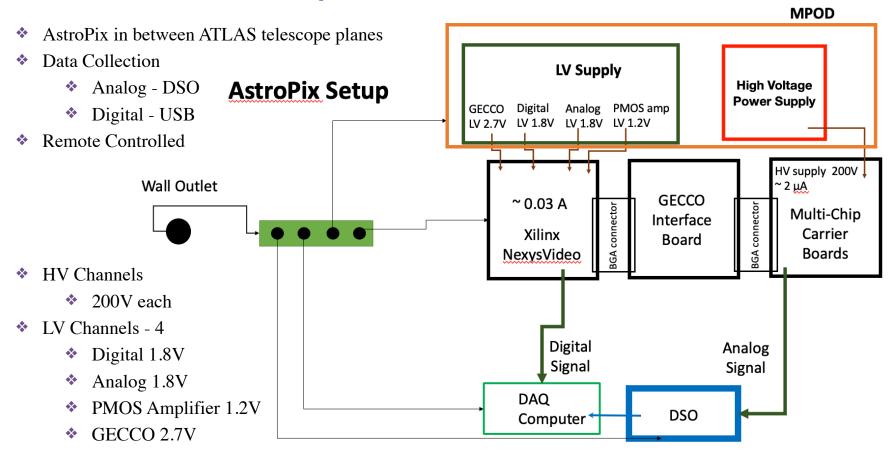
#### Irradiation test

- 400 MeV proton (minimum 4.5E12 protons/min) at the FNAL ITA Facility
- Latch-up tests by NASA with heavy ions (from Argon to Xenon with an atomic tune of 16 MeV/a.m.u.) at LBNL (BASE)

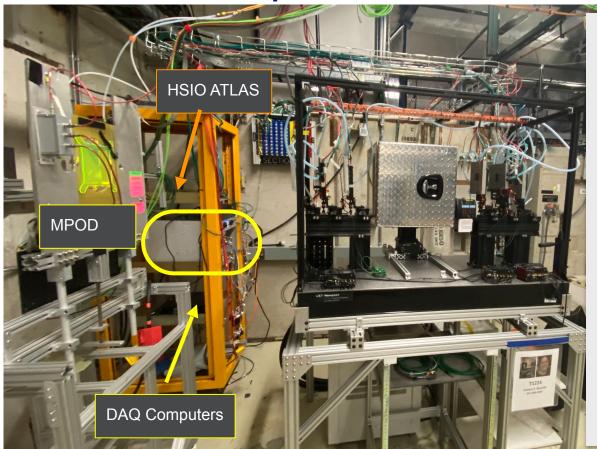




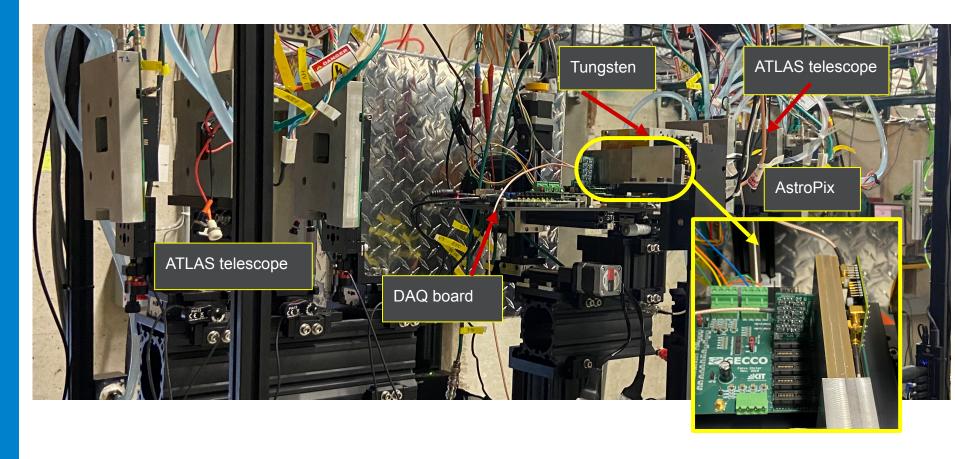


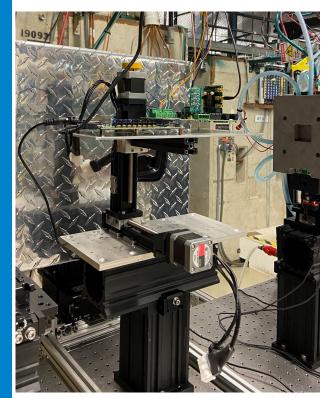


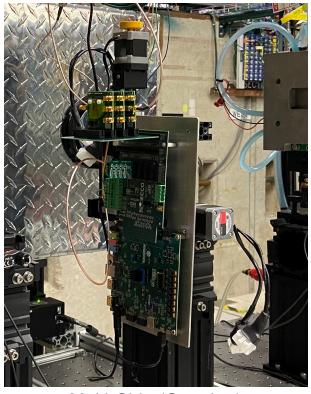




- Technical Scope of Work here
- \* How to Create here
- \* TSW- 1224
- ATLAS Pixel
  - Jessica Metcalfe
- Section 6.2A
- 6 ATLAS FEI4 telescope planes
- ♦ DUT cold box (-30 °C)
- \* Breadboard 48" x 24"
- AstroPix is placed in center (cold box pushed back)



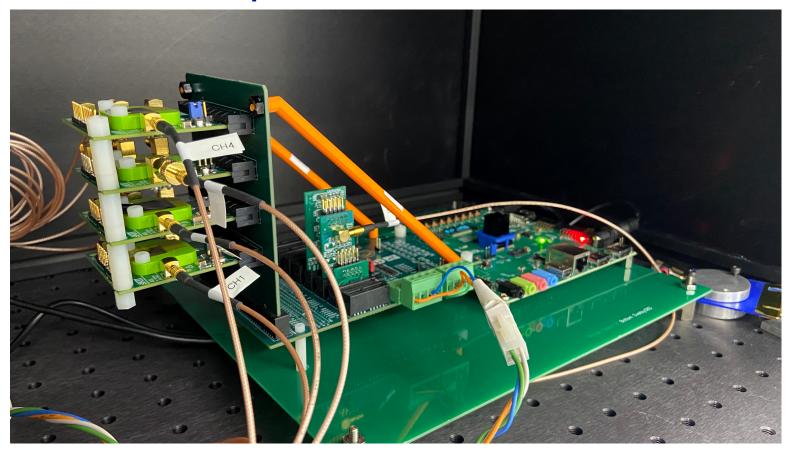




Single Chip

Single Chip w/ Tungsten

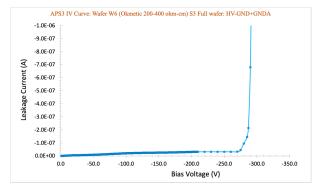
Multi-Chip (Ongoing)

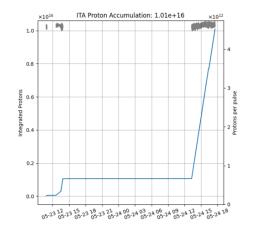


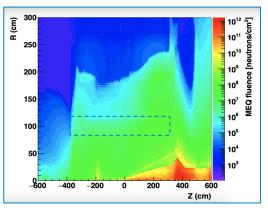
# **Snapshots from the Sensor Irradiations**

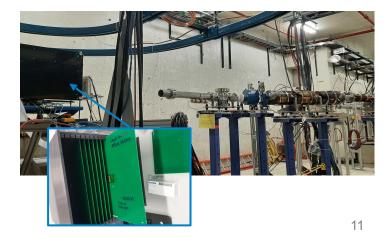
- 9 samples of AstroPix v2 chips prepared for the passive irradiation in the FNAL MTA Facility
- IV and CV measurements performed for the v2 chips before irradiations
  - Same measurements will be repeated post irradiation
- Plan to irradiare next 6 v3 chips and run active irradiation tests

Nb of samples	Doses (400 MeV protons)
3	4.50E+13
3	1.08E+15
1	1.01E+16
1	5.02E+16









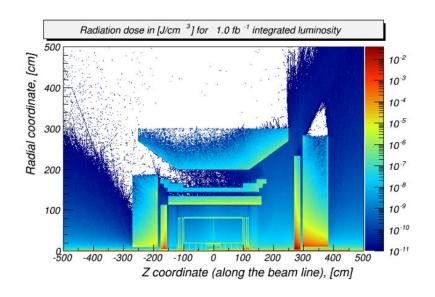
## AstroPix FTBF R&D

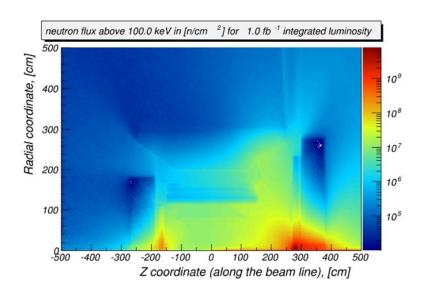
- 1. AstroPix chip performance studies with test beam
  - 1. DAQ with different triggering schemes, a benchmark set for the test with v3 chip 🗸
  - 2. Initial data obtained with single layer setup with and without W-radiator, in self-triggering streaming data mode
  - 3. Multilayer AstroPix standalone telescope with radiator layer 🚧
  - 4. External trigger from existing ATLAS telescope to study tracking efficiency, position resolution, etc.
  - 5. External trigger and multilayer readouts are being currently tested at FNAL MTest Facility \*\*\*

    \*\*Irradiation tost with v2 and v3 chips, irradiation plan tosted.
- 2. Irradiation test with v2 and v3 chips, irradiation plan tested
  - 1. v2 chip pre-irrad characterization and Irradiation performed at different radiation doses 🗸
  - 2. Irradiation beam test Ongoing at FNAL MTA Facility
    - 1. Passive Irradiation of v2 chips is completed, v3 chip will be irradiated this week
    - 2. Active Irradiation of the v3 chip will be performed in the coming weeks

# **Backup**

## **Ionization radiation and neutron flux**





- Maximum ionizing radiation dose from e+p collisions at the highest EIC luminosity (10<sup>34</sup>cm<sup>-2</sup>s<sup>-1</sup>): ~1 Rad/year
- Neutron flux: 10<sup>8</sup> neutrons/cm<sup>2</sup> per year at the top luminosity (two order of magnitude lower than the near-beam-line detectors)



